ON Semiconductor®

Final Product/Process Change Notification

Document # : FPCN22647XH
Issue Date: 10 October 2019

Title of Change:	Mold Compound Change attributed to an End of Life of Samsung SDI EMC for products in TO3P-5L.
Proposed first ship date:	17 January 2020
Contact information:	Contact your local ON Semiconductor Sales Office or <sangseop.kim@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Lake.Wang@onsemi.com>.
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>
Change Part Identification:	Material marked with date code 1950 or later will be assembled with new mold compound.
Change Category:	☐ Wafer Fab Change ☑ Assembly Change ☐ Test Change ☐ Other _____

Change Sub-Category(s):

☐ Manufacturing Site Addition	☑ Material Change	☐ Datasheet/Product Doc change
☐ Manufacturing Site Transfer	☐ Product specific change	☐ Shipping/Packaging/Marking
☐ Manufacturing Process Change		☐ Other: _____

Sites Affected:	ON Semiconductor Sites: ON Suzhou, China	External Foundry/Subcon Sites: None

Description and Purpose:

ON Semiconductor would like to notify our customers of our qualification of a change in mold compound for the product listed in this FPCN at our ON Suzhou, China facility.

	Before Change Description	After Change Description
Mold Compound (TO3P_5L)	SI7200DX2; Supplier: Samsung SDI	KTMC1050GFB; Supplier: KCC

This change was necessitated by an End of Life (EOL) notification from Samsung for the mold compounds listed above.

Reliability Data Summary:

QV DEVICE NAME: FS7M0880TU
RMS : K56633, U59348
PACKAGE : TO3P_5L

Test	Specification	Condition	Interval	Results
HTBB	M750-1048	Ta = 125°C for device, bias = 100% of max rated BV	1008 hrs	0/77
HTOL	JESD22-A108	Tj = 140°C for device, bias = 100% of max rated Vcc	1008 hrs	0/77
HTSL	JESD22-A103	Ta = 150°C	1008 hrs	0/77
TC	JESD22-A104	Ta=-55°C ~150°C	1000 cyc	0/77
HAST	JESD22-A110	Temp= +130°C, RH=85% , p = 18.8 psig, bias	96 hrs	0/77
HVTHB	-	168 hour moisture soak at Ta=85°C/85% RH followed by 168 hours biased at maximum rated voltage at Tj=85°C/60% RH.	168 hrs	0/77
RSH	JESD22-B106	Ta = 265°C, 10 sec	-	0/10
SD	J-STD-002	Ta=245°C 5 sec dwell	-	0/15
Tri-temp	-	Tri-Temperature, Per 48A	-	0/30
TR	-	Thermal Resistance	-	0/10
PD	-	Per Case Outline	-	0/10

Electrical Characteristic Summary:

Electrical characteristics are not impacted by this change. Electrical comparison reports are available upon request.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal.**

Part Number	Qualification Vehicle
FS7M0880TU	FS7M0880TU
FS7M0880YDTU	